PREPARED BY:	DATE:			SPEC. No.	ED-94054D
m mitarii (11. 18 295	SHA	RP	ISSUE	June14, 1996
				PAGE	10 Pages
APPROVED BY:	DATE:	ELECTRONIC COM GROUP SHARP CC		REPRESENT	TATIVE DIVISION
J yoshikuwa	june 17 1995	SPECIFICA	ATION	OPTO-ELEC	TRONIC DEVICES DIV
	DEVICE SP	ECIFICATION FOR	Business d	ealing name	$\overline{}$
	РНОТС	COUPLER	PC817X	PC817X6	
	MODEL No.		PC817X1 PC817X2		3
	P	2817	PC817X3 PC817X4 PC817X5	PC817X0	
	<u> </u>				
		clude materials protected ur ause anyone to reproduce th			n ("Sharp").
in these spe for any dam	cification sheets age resulting fro	ease observe the absolute ma , as well as the precautions of m use of the product which ed in these specification shee	mentioned below. does not comply w	Sharp assumes ith the absolute	no responsibility maximum ratings
(Precautio					
	OA equipment Telecommunica	signed for use in the followin • Audio visual equipment tion equipment (Terminal) es • Computers		s	
If	the use of the p	roduct in the above applicati sure to observe the precau			
the	e safety design of d safety when th	res, such as fail-safe design the overall system and equi is product is used for equipn nd precision, such as ;	pment, should be i	taken to ensure	reliability
		control and safety equipmen • Gas leakage sensor break			nont
1 1	Other safety equ		ers Rescue and	security equipi	
		this product for equipment w on and precision, such as ;	hich require extrem	mely high reliab	oility
[Γ·	Space equipmer	nt • Telecommunication equ ontrol equipment • Medica	ipment (for trunk l equipment	lines)	
		consult with a Sharp sales r ation of the above three para		ere are any ques	stions
3. Please contac	t and consult w	ith a Sharp sales representa	itive for any questi	ons about this p	product.
CUSTOME	R'S APPROVA	L ·	DATE PRESENTEI BY) J.1	2) (
DATE			Departr Enginee	umura, nent General I ering Dept.,II	
BY			ELECO	lectronic Devic M Group CORPORATIO	

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1. Application

This specification applies to the outline and characteristics of photocoupler Model No. PC817series.

2. Outline

Refer to the attached drawing No. CY6961K02.

3. Ratings and characteristics

Refer to the attached sheet, page 3 to 6.

4. Reliability

Refer to the attached sheet, page 7.

5. Incoming inspection

Refer to the attached sheet, page 8.

6. Supplement

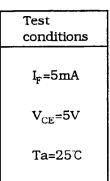
- 6.1 Isolation voltage shall be measured in the following method.
- (1) Short between anode to cathode on the primary side and between collector to emitter on the secondary side.
- (2) The dielectric withstand tester with zero-cross circuit shall be used.
- (3) The wave form of applied voltage shall be a sine wave.(It is recommended that the isolation voltage be measured in insulation oil.)

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6.2 Business dealing name

("O" mark indicates business dealing name of ordered product)

Ordered product	Business dealing name	Rank mark	Ic (mA)
	PC817X	A, B, C, D or no mark	2.5 to 30
	PC817X1	Α	4.0 to 8.0
	PC817X2	В	6.5 to 13
	PC817X3	С	10 to 20
	PC817X4	D	15 to 30
	PC817X5	A or B	4.0 to 13
	PC817X6	B or C	6.5 to 20
	PC817X7	C or D	10 to 30
	PC817X8	A, B or C	4.0 to 20
	PC817X9	B, C or D	6.5 to 30
	PC817X0	A, B, C or D	4.0 to 30



6.3 This Model is approved by UL.

Approved Model No. : PC817

UL file No. : E64380

6.4 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

7. Notes

Refer to the attached sheet-1-1, 2.

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3. Ratings and characteristics

3.1 Absolute maximum ratings

Parameter		Symbol	Rating	Unit
	*1 Forward current	I _F	50	mA
Input	*2 Peak forward current	I _{FM}	1	A
Input	Reverse voltage	V _R	6	v
	*1 Power dissipation	Р	70	mW
	Collector-emitter voltage	V _{CEO}	35	v
Output	Emitter-collector voltage	V _{ECO}	6	v
Output	Collector current	Ic	50	mA
	*1 Collector power dissipation	Pc	150	mW
	*1 Total power dissipation	Ptot	200	mW
*3 Isolation voltage Operating temperature Storage temperature		Viso	5	kVrms
		Topr	-30 to +100	Ĉ
		Tstg	-55 to +125	Ĉ
	*4 Soldering temperature	Tsol	260	Ĉ

*1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1 to 4.

*2 Pulse width $\leq 100 \ \mu$ s, Duty ratio : 0.001 (Refer to Fig. 5)

*3 AC for 1 min, 40 to 60%RH

*4 For 10 s

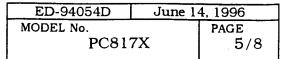
Ta=25°C

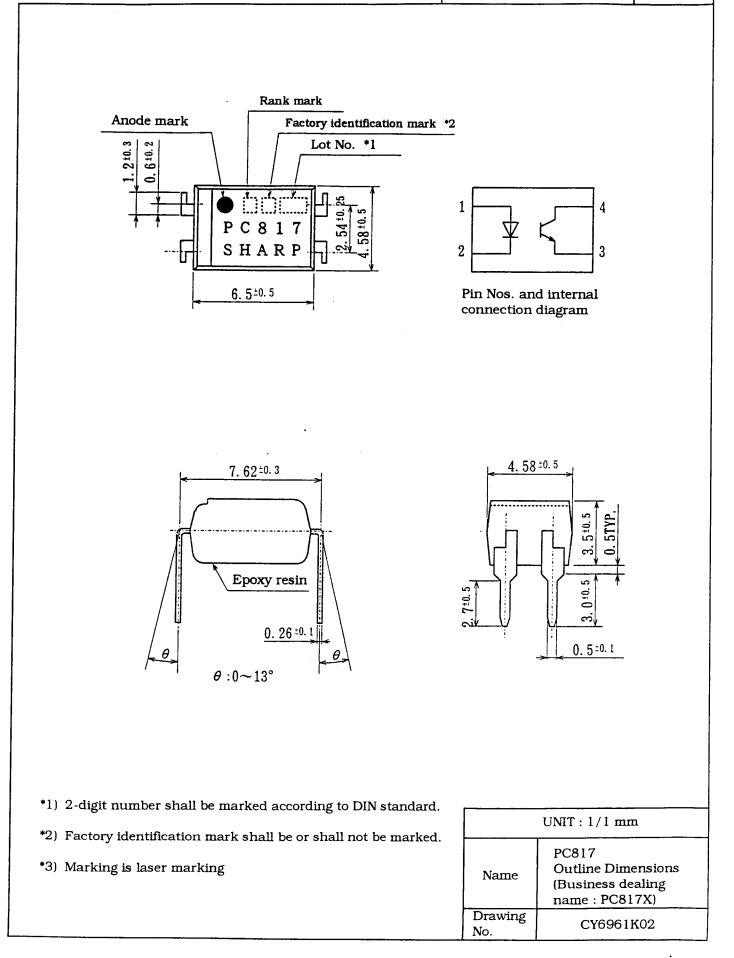
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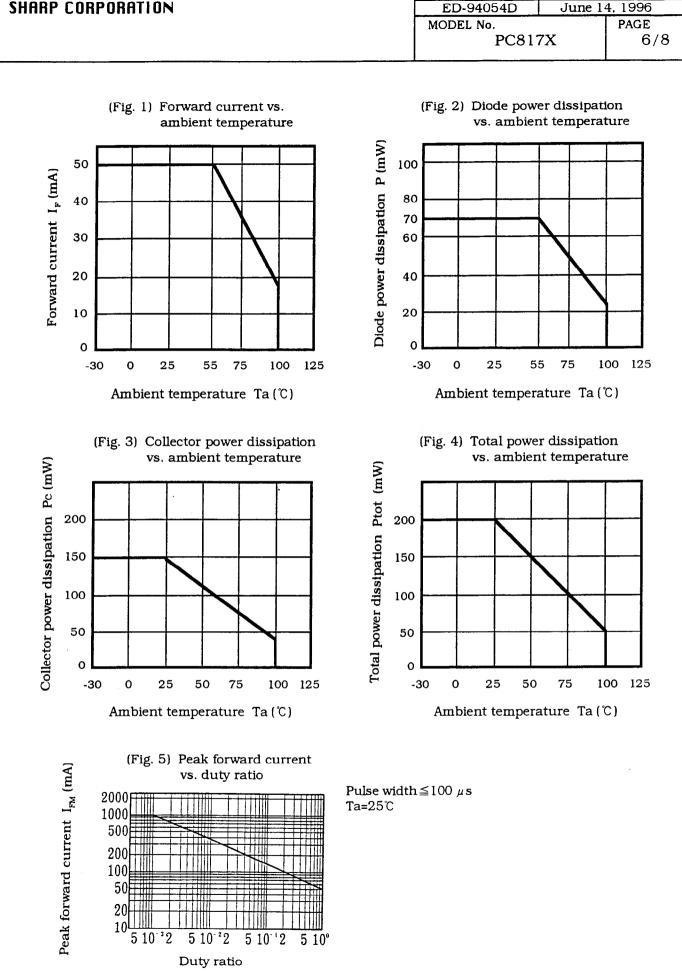
3.2 Electro-optical characteristics

Ta=25°C

	Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
	Forward voltage	V _F	V _F I _F =20mA		1.2	1.4	v
Input	Peak forward voltage	V _{FM}	I _{FM} =0.5A	-	-	3.0	v
при	Reverse current	I _R	V _R =4V	-	-	10	μA
	Terminal capacitance	Ct	V=0, f=1kHz	-	30	250	pF
	Dark current	I _{CEO}	V _{CE} =20V, I _F =0	-	-	100	nA
Output	Collector-emitter breakdown voltage	BV _{CEO}	Ic=0.1mA I _F =0	35	-	-	v
	Emitter-collector breakdown voltage	BV _{ECO}	$I_{\rm E}$ =10 µA, $I_{\rm F}$ =0	6	-	-	v
	Collector current	Ic	I _F =5mA, V _{CE} =5V	2.5	-	30	mA
	Collector-emitter saturation voltage	$V_{CE(sat)}$.	I _F =20mA Ic=1mA	-	0.1	0.2	v
Transfer	Isolation resistance	R _{ISO}	DC500V 40 to 60%RH	5×10 ¹⁰	10 ¹¹	-	Ω
charac- teristics	Floating capacitance	Cf	V=0, f=1MHz	-	0.6	1.0	pF
	Cut-off frequency	fc	V_{CE} =5V, Ic=2mA R _L =100 Q, -3dB	-	80	-	kHz
	Rise time	tr	V _{CE} =2V Ic=2mA	-	4	18	μs
	Fall time	ťſ	$R_{L}=100 \Omega$	-	3	18	μs







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4. Reliability

The reliability of products shall be satisfied with items listed below.

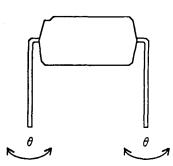
Confidence level : 90% LTPD : 10%/20%

		LIFD . 10/0/	20.0
Test Items	Test Conditions *1	Failure Judgement Criteria	Samples (n) Defective(C)
Solderability *2	230°C, 5 s		n=11, C=0
Soldering heat	260°C, 10 s		n=11, C=0
Terminal strength (Tension)	Weight : 5N 5 s/each terminal	$V_F > U \times 1.2$	n=11, C=0
Terminal strength (Bending) *3	Weight : 2.5N 2 times/each terminal	$I_R > U \times 2$	n=11, C=0
Mechanical shock	$\frac{15000 \text{m/s}^2, 0.5 \text{ms}}{3 \text{ times}/\pm X, \pm Y, \pm Z \text{ direction}}$	$I_{CEO} > U \times 2$ $I_{CEO} < L \times 0.7$	n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/4min 200m/s ² 4 times/ X, Y, Z direction	$V_{CE(sat)}$ >U×1.2	n=11, C=0
Temperature cycling	1 cycle -55 °C to +125 °C (30min) (30min) 20 cycles test	U : Upper	n=22,C=0
High temp. and high humidity storage	+60°C, 90%RH, 1000h	specification limit	n=22,C=0
High temp. storage	+125°C, 1000h	L : Lower specification	n=22,C=0
Low temp. storage	-55°C, 1000h	limit	n=22,C=0
Operation life	I _F =50mA, Ptot=200mW Ta=25°C, 1000h		n=22,C=0

*1 Test method, conforms to JIS C 7021.

*2 Solder shall adhere at the area of 95% or more of immersed portion of lead and pin hole or other holes shall not be concentrated on one portion.

*3 Terminal bending direction is shown below.



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5. Incoming inspection

5.1 Inspection items

(1) Electrical characteristics

 V_F , I_R , I_{CEO} , $V_{CE(sat)}$, Ic, R_{ISO} , Viso

(2) Appearance

5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

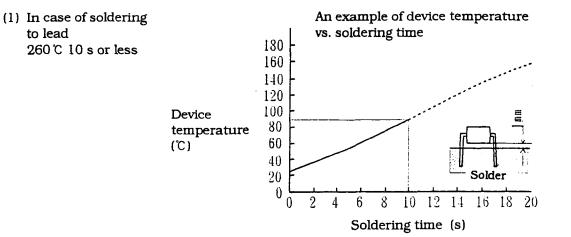
Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.1
Minor defect	Appearance defect except the above mentioned.	0.4

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PC81'	7X Attach	

	Precautions for Photocouplers
1	For cleaning
((1) Solvent cleaning : Solvent temperature 45℃ or less Immersion for 3 min or less
((2) Ultrasonic cleaning : The affect to device by ultrasonic cleaning is different by cleaning bath size, ultrasonic power output, cleaning time, PWB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.
	Applicable solvent : Ethyl alcohol, Methyl alcohol Freon TE · TF, Diflon-solvent S3-E
	Please refrain form using Chloro Fluoro Carbon type solvent to clean device as much as possible since it is internationally restricted to protect the ozonosphere. Before you use alternative solvent you are requested to confirm that it does not attack package resin.
	The LED used in the Photocoupler generally decreases the light emission power by operation. In case of long operation time, please design the circuit with considering the degradation of the light emission power of the LED. (50%/5years)

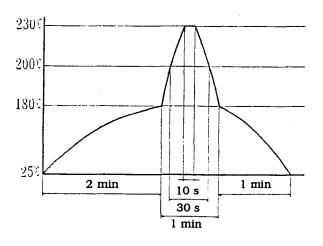
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3. Precautions for Soldering Photocouplers



(2) If solder reflow :

It is recommended that only one soldering be done at the temperature and the time within the temperature profile as shown in the figure.



(3) Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item (2). Also avoid immersing the resin part in the solder.